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## U.S. PATENT DOCUMENTS

| EXAMINER<br>INITIAL |    | DOCUMENT NUMBER | DATE    | NAME          | CLASS | SUBCLASS | FILING DATE<br>IF APPROPRIATE |
|---------------------|----|-----------------|---------|---------------|-------|----------|-------------------------------|
| 88                  | AA | 5 6 5 2 0 4 2   | 7/29/97 | KAWAKITA ETAL | 428   | 209      |                               |
|                     | AB |                 |         |               |       |          |                               |
|                     | AC |                 |         |               |       |          |                               |
|                     | AD |                 |         |               |       |          |                               |
|                     | AE |                 |         |               |       |          |                               |
|                     | AF |                 |         |               |       |          |                               |
|                     | AG |                 |         |               |       |          |                               |
|                     | AH |                 |         |               |       |          |                               |
|                     | AI |                 |         |               |       |          |                               |
|                     | AJ |                 |         |               |       |          |                               |
|                     | AK |                 |         |               |       |          |                               |

## FOREIGN PATENT DOCUMENTS

|  |    | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION |    |
|--|----|-----------------|------|---------|-------|----------|-------------|----|
|  |    |                 |      |         |       |          | YES         | NO |
|  | AL |                 |      |         |       |          |             |    |
|  | AM |                 |      |         |       |          |             |    |
|  | AN |                 |      |         |       |          |             |    |
|  | AO |                 |      |         |       |          |             |    |
|  | AP |                 |      |         |       |          |             |    |

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

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| 88 | AR | R LASKY, "NEW PCB TECHNOLOGIES EMERGE FOR HIGH-DENSITY INTERCONNECT"<br>ELECTRONIC PACKAGING AND PRODUCTION, APRIL 1998, PAGES 75-78   |
| 88 | AS | HAYE ET AL, "DEVELOPMENT OF HIGH CONDUCTIVITY LEAD (Pb)-FREE CONDUCTING ADHESIVES"<br>IEEE TRANSACTIONS ON COMPONENTS, MANUFACTURING TECHNOLOGY, PART A, VOL 21, NO 1, MARCH 1998, PAGES 18-22   |
| 88 | AT | HANG ET AL, "DEVELOPMENT OF LOW COST, LOW TEMPERATURE CONDUCTIVE ADHESIVES", PROCEEDINGS<br>OF THE 48TH ELECTRONIC COMPONENTS & TECHNOLOGY CONFERENCE, SEATTLE, WASH., MAY 1998, PAGES 1031-1035 |

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Jonathan Johnson

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|  | AP |                 |      |         |       |          |             |    |

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

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| 88 | AU | GONZALEZ ET AL, "EPOXY-BASED AQUEOUS-PROCESSABLE PHOTOELECTRIC DRY FILM AND CONDUCTIVE VIA PLOT FOR PCB BUILDUP AND IC PACKAGING," PAGE 78TH ELECTRONIC COMPONENTS TECH. CONF. SEATTLE WASH. NOV 1998, P139-143 |
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